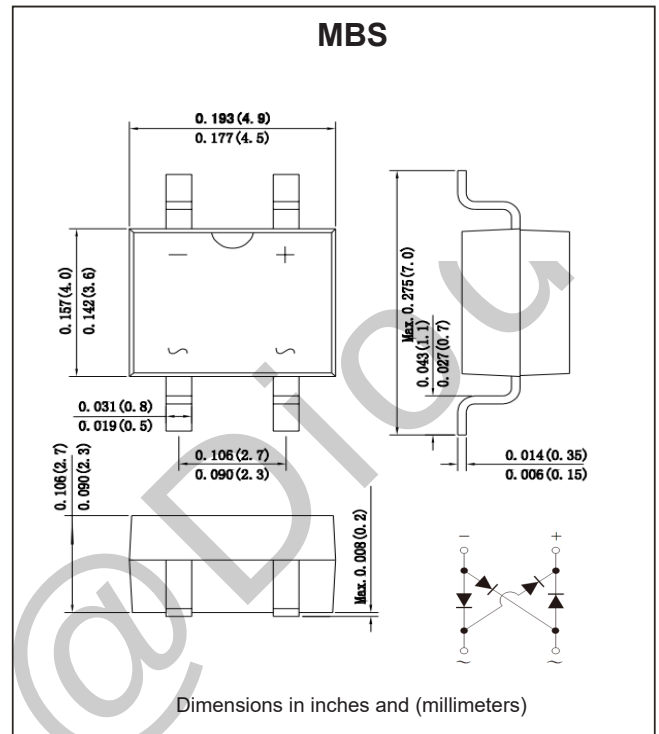


Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed 250°C/10 seconds at terminals

MECHANICAL DATA

- Molded plastic body
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Polarity symbol marking on body
- Mounting Position: Any
- Weight : 0.004 ounce, 0.118 grams



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MB2S	MB4S	MB6S	MB8S	MB10S	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$ On glass-epoxy P.C.B (Note 1)	$I_{(AV)}$	0.8					A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	30.0					A
Rating for fusing ($t=8.3\text{ms}$, $T_a=25^\circ\text{C}$)	I_t^2	3.74					A^2s
Maximum instantaneous forward voltage at 0.8A	V_F	1.10					V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	5.0 500					μA
Typical junction capacitance (Note 2)	C_J	15.0					pF
Typical thermal resistance	R_{JA}	85.0					$^\circ\text{C/W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150					$^\circ\text{C}$

Note: 1. Mounted on glass epoxy PC board with 1.3*1.3mm solder pad
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

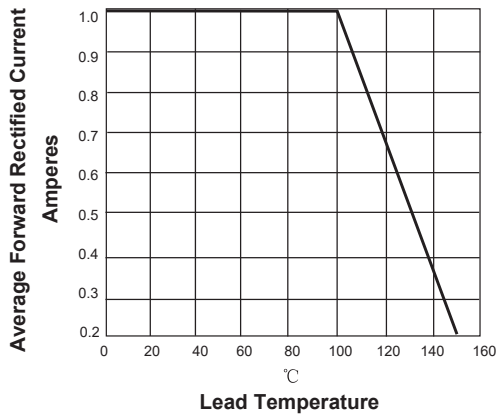


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

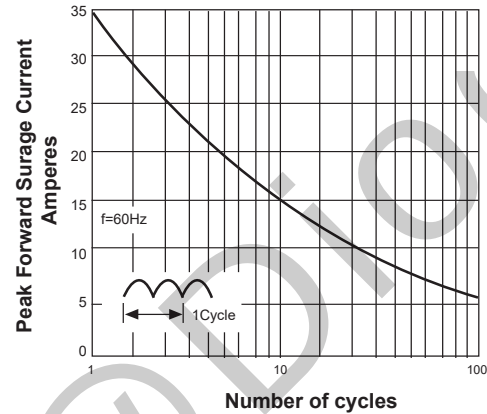


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

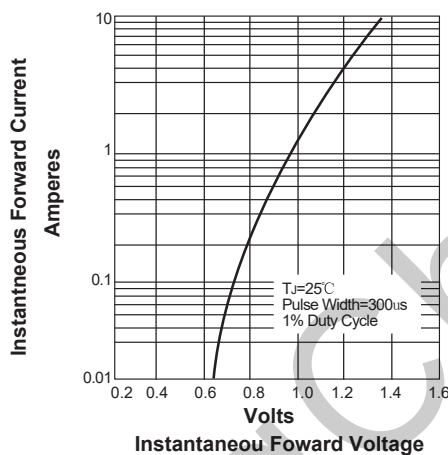
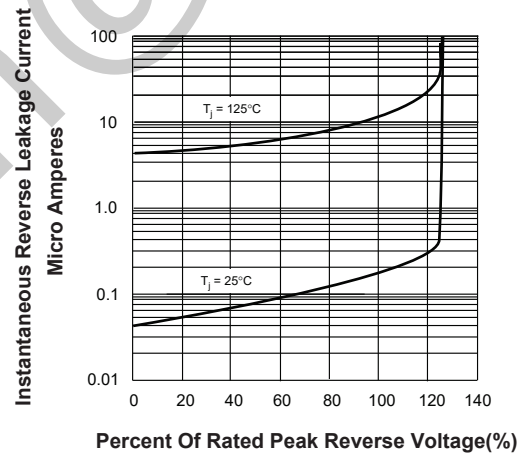
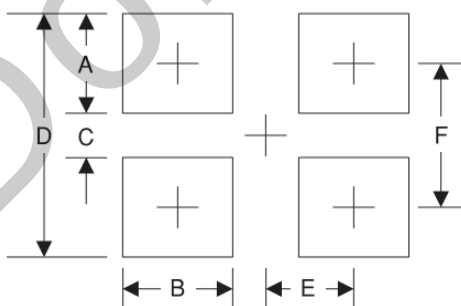


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

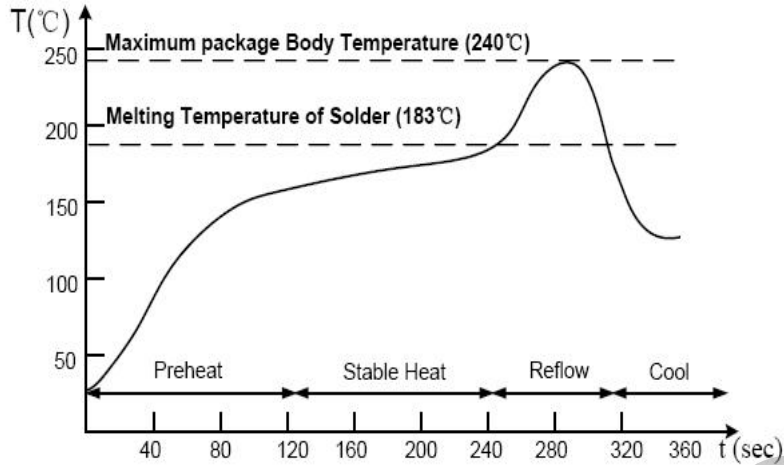


Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.7	0.067
B	1.0	0.039
C	4.40	0.173
D	8.10	0.319
E	1.25	0.049
F	6.30	0.248

Suggested Soldering Temperature Profile

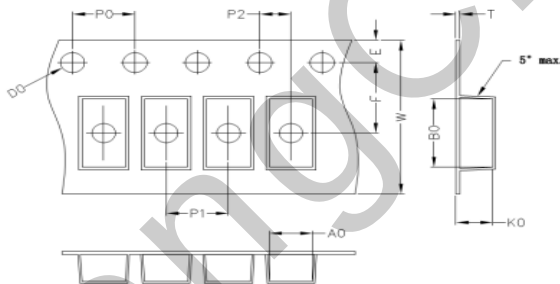


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
5.10	7.20	2.88	1.55	1.75	5.50
P0	P1	P2	T	W	Tolerance
4.0	8.0	2.0	0.25	12	0.1

Important Notice

DongChen Electronics reserves the right to make changes without further notice to any products herein.

DongChen Electronics makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does DongChen Electronics assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages.

“Typical” parameters which may be provided in DongChen Electronics data sheets and/or specifications can and do vary in different applications and actual performance may vary over time.

All operating parameters, including “Typicals,” must be validated for each customer application by the customer’s technical experts.

DongChen Electronics does not convey any license under its patent rights nor the rights of others.

The products listed in this document are designed to be used with ordinary electronic equipment or devices.

Should you intend to use these products with equipment or devices which require an extremely high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, aerospace machinery, nuclear-reactor controllers, fuel controllers, and other safety devices), please be sure to consult with our sales representative in advance.

Head Office

Contact Information:

DongChen Electronics Co.,Ltd.

Address: 2F., No.407, Sec. 2, Longgang Rd.,Zhongli Dist.,
Taoyuan City 32097, Taiwan (R.O.C.)

Tel: 03-284-1808

Fax: 03-284-1404

Mail:dc@dongchen.com.tw

Web:www.dongchen.com.tw